

Connector for Memory Stick Micro™

SCNA Series



Minimum mounting area for compact devices.

For SD Memory Card

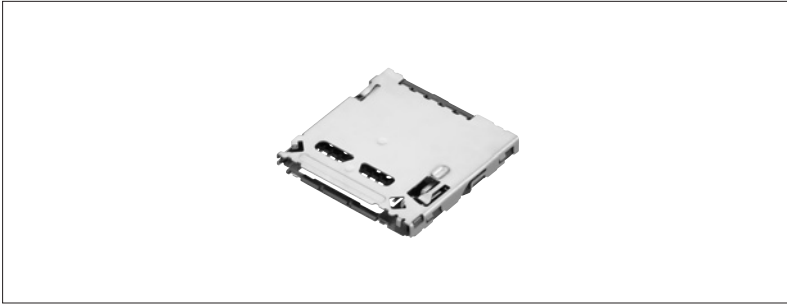
For miniSD™ Card

For microSD™ Card

For W-SIM

For Memory Stick Micro™

For Memory Stick™



Features

- Minimized mounting area prevents negation of size advantage of the card.

Applications

- For mobile phones, personal digital assistants, digital still cameras, compact audio equipment

Typical Specifications

Items		Specifications
Structure	Applicable media	Memory Stick Micro™
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	-25°C to +60°C
	Voltage proof	250V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Insertion and removal cycle	12,000cycles

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCNA1A0300

Combine Type

For Compact Flash™

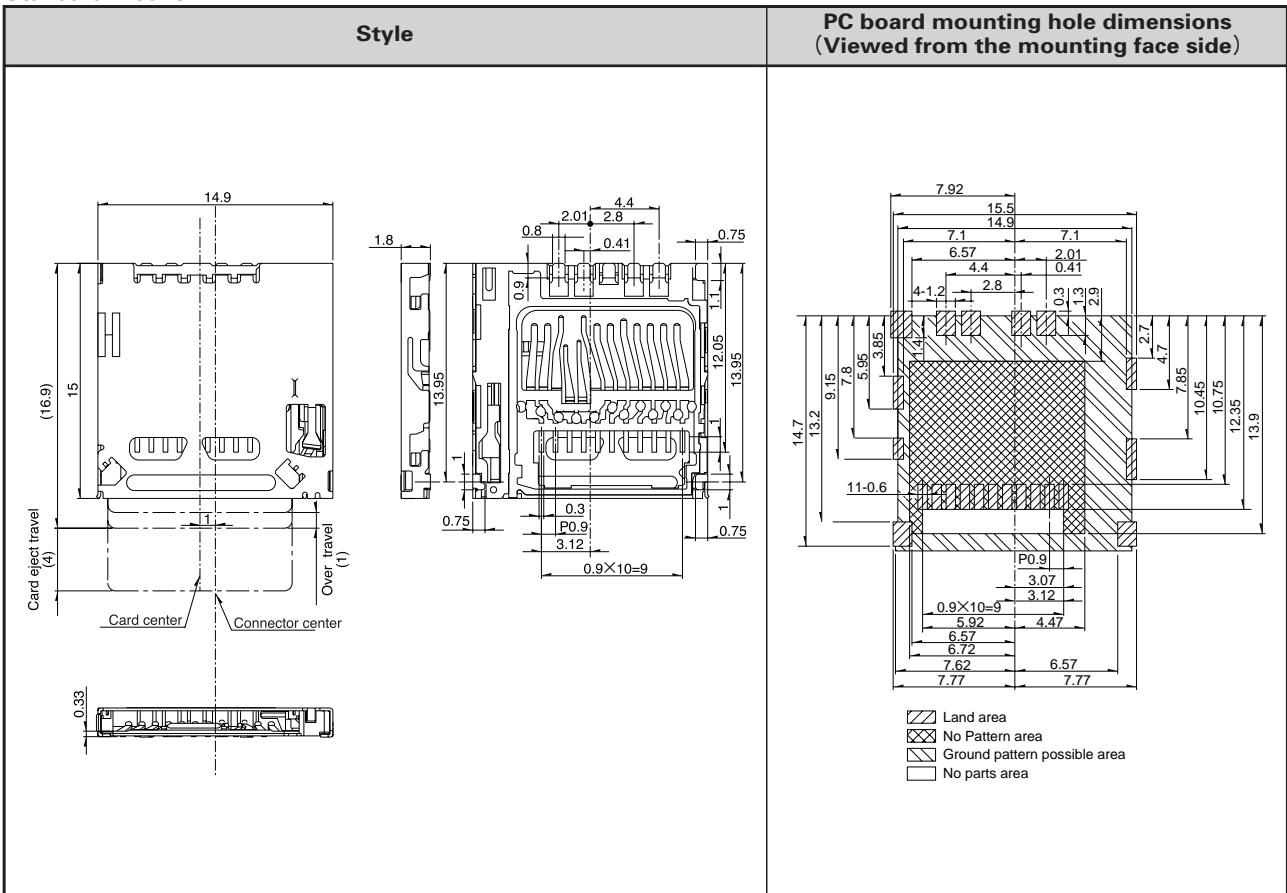
For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Dimensions
Standard mount

Unit:mm



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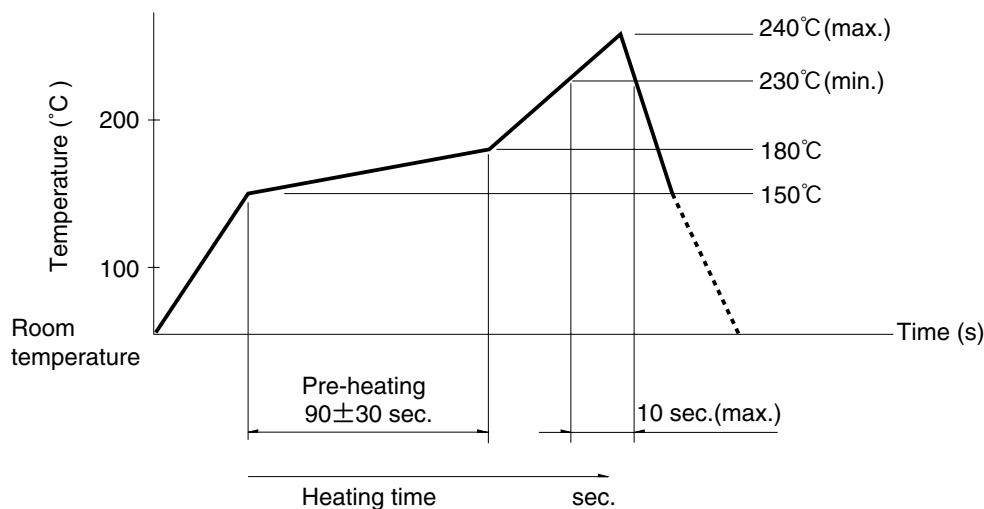
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. This product has been designed and manufactured for use in ordinary electronic equipment, such as AV equipment, electric home appliances, office machines and communication equipment. In case of using the products for highly sensitive applications such as medical, aviation, aerospace and security, the set makers shall require to include measures necessary to meet product safety requirements of such specific applications. Such measure may include additional protection circuits and redundant circuits, for example.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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